

New isolated power modules advance power density

TI's breakthrough isolated power modules with IsoShield™ packaging technology shrink power solution size by up to 70%.

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NEW

DC/DC CONTROLLERS
LM5192-Q1 [PREVIEW](#)
Automotive, 80V, synchronous buck controller with constant current and constant voltage with I2C
Approx. price (USD) 1ku | 2.05

NEW

LIN TRANSCEIVERS
TLINB21-Q1 [PREVIEW](#)
Automotive Fault-Protected LIN Transceiver with Inhibit and WAKE
Approx. price (USD) 1ku | 0.29

NEW

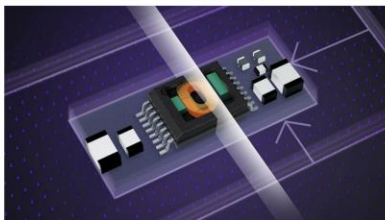
CLOCK BUFFERS
LMK1C1106-Q1 [PREVIEW](#)
6-channel output LVCMOS 1.8-V buffer for Automotive
Approx. price (USD) 1ku | 1.36

23 MAR 2026 | COMPANY BLOG

Why packaging is the next frontier in power design innovation

As power systems demand more capability within fixed areas, packaging innovations enable greater integration, safety and performance

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Our passion

At our core, we have a passion to create a better world by making electronics more affordable through semiconductors. This passion is alive today as we continue to pioneer advances in integrated circuits. Each generation of innovation builds upon the last to make technology smaller, more efficient, more reliable and more affordable – opening new markets and making it possible for semiconductors to go into electronics everywhere. We think of this as Engineering Progress.

[→ Who we are](#) [→ What we do](#)

Join our team

Our work is challenging and fast-paced, and it's our people that make us great. Do you want to change the world and love your job? Join us.

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Our commitment to corporate citizenship

[Download our "2024 Corporate Citizenship Report"](#)

90% Percentage of shipped semiconductor products considered green that meet low-halogen industry requirements.

29% Reduction of our greenhouse gas (GHG) emissions from 2015 to 2024 - making progress towards our 25% reduction goal.

*Numbers accurate as of 2024

31% of water was reused by our global manufacturing operations in 2024.

88% of solid waste materials generated were diverted from landfills in 2024.

30+ Honors for talent development and workforce programs.

\$57 million in philanthropic giving, in partnership with the TI Foundation, TI employees and retirees, to support our local communities.

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